

Electronic Patent Application Fee Transmittal

Application Number:	10706212			
Filing Date:	12-Nov-2003			
Title of Invention:	Wafer back side coating to balance stress from passivation layer on front of wafer and be used as a die attach adhesive			
First Named Inventor/Applicant Name:	Michael E. Connell			
Filer:	James R. Duzan/Sharley Thayne			
Attorney Docket Number:	2269-5083.1US (01-0428.01)			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180